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JUL 27 2004

TECH CENTER 2000

EFS ID: 65085

Application ID: 09972011



Title of Invention: Method and arrangement for layout and manufacture of nonmanhattan semiconductor integrated circuit using simulated euclidean wiring

First Named Inventor: Steven Teig

Domestic/Foreign Application: Domestic Application

Filing Date: 2001-10-05

Effective Receipt Date: 2004-07-22

Submission Type: Information Disclosure Statement

Filing Type:

Confirmation number: 5250

Attorney Docket Number: SPLX.P0068

Total Fees Authorized: 180.0

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Electronic Version v1.1
Stylesheet Version v1.1.0

JUL 27 2004

TECH CENTER 2000

Title of Invention	Method and arrangement for layout and manufacture of nonmanhattan semiconductor integrated circuit using simulated euclidean wiring
Application Number:	09/972011 
Date:	2001-10-05
First Named Applicant:	Steven Teig
Confirmation Number:	5250
Attorney Docket Number:	SPLX.P0068

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Submitted by:	Elec. Sign.	Sign. Capacity
Mani Adeli Registered Number: 39,585	/Mani Adeli/	Attorney

Documents being submitted	Files
us-fee-sheet	SPLX.P0068-usfees.xml us-fee-sheet.xsl us-fee-sheet.dtd
us-ids	SPLX.P0068-usidst.xml us-ids.dtd us-ids.xsl

Comments

This Information Disclosure Statement is submitted after receipt of a first Office Action on the merits but before the Final Office Action. Accordingly, a fee is required. The requisite fee is included with this electronic submission of the Information Disclosure Statement. Applicants hereby request that the one submitted fee be accepted for the second and any subsequent submission.



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Electronic Version v08

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TECH CENTER 2800

Title of Invention	Method and arrangement for layout and manufacture of nonmanhattan semiconductor integrated circuit using simulated euclidean wiring										
Application Number:	09/972011										
Date:	2001-10-05										
First Named Applicant:	Steven Teig										
Attorney Docket Number:	SPLX.P0068										
Art Unit:	2825										
Examiner:	Helen B. Rossoshek										
TOTAL FEE AUTHORIZED \$180											
Patent fees are subject to annual revisions on or about October 1st of each year.											
BASIC FILING FEE											
<table border="1"> <thead> <tr> <th>Fee Description</th> <th>Fee Code</th> <th>Amount \$</th> <th>Fee Paid \$</th> </tr> </thead> <tbody> <tr> <td>Submission Of Information Disclosure Stmt Fee</td> <td>1806</td> <td>180</td> <td>180</td> </tr> </tbody> </table>				Fee Description	Fee Code	Amount \$	Fee Paid \$	Submission Of Information Disclosure Stmt Fee	1806	180	180
Fee Description	Fee Code	Amount \$	Fee Paid \$								
Submission Of Information Disclosure Stmt Fee	1806	180	180								
AUTHORIZED BILLING INFORMATION											
The commissioner is hereby authorized to charge indicated fees and credit any overpayments to:											
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ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18
Stylesheet Version v18.0

Title of Invention	Method and arrangement for layout and manufacture of nonmanhattan semiconductor integrated circuit using simulated euclidean wiring						
Application Number:	09/972011						
Confirmation Number:	5250						
First Named Applicant:	Steven Teig						
Attorney Docket Number:	SPLX.P0068						
Art Unit:	2825						
Examiner:	Helen B. Rossoshek						
Search string:	(4855253 or 5541005 or 5635736 or 5637920 or 5640327 or 5646830 or 5650653 or 5689433 or 5723908 or 5784289 or 5801385 or 5811863 or 5822214 or 5880969 or 5889329 or 5980093 or 6150193 or 6260183 or 6262487 or 6263475 or 6301686 or 6307256 or 6316838 or 6324674 or 6412097 or 6448591 or 6516455 or 20010009031 or 20030025205).pn.						
US Patent Documents							
Note: Applicant is not required to submit a paper copy of cited US Patent Documents							
init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
	1	4855253	1989-08-08	Weber			
	2	5541005	1996-07-30	Bezama et al.			
	3	5635736	1997-06-03	Funaki et al.			
	4	5637920	1997-06-10	Loo			
	5	5640327	1997-06-17	Ting			
	6	5646830	1997-07-08	Nagano			
	7	5650653	1997-07-22	Rostoker et al.			
	8	5689433	1997-11-18	Edwards			
	9	5723908	1998-03-03	Fuchida et al.			
	10	5784289	1998-07-21	Wang			
	11	5801385	1998-09-01	Endo et al.			

12	5811863	1998-09-22	Rostoker et al.	
13	5822214	1998-10-13	Rostoker et al.	
14	5880969	1999-03-09	Hama et al.	
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18	6260183	2001-07-10	Raspopovic et al.	B1
19	6262487	2001-07-17	Igarashi et al.	B1
20	6263475	2001-07-17	Toyonaga et al.	B1
21	6301686	2001-10-09	Kikuchi et al.	B1
22	6307256	2001-10-23	Chiang et al.	B1
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26	6448591	2002-09-10	Juengling	B1
27	6516455	2003-02-04	Teig et al.	B1

US Published Applications

Note: Applicant is not required to submit a paper copy of cited US Published Applications

init	Cite.No.	Pub. No.	Date	Applicant	Kind	Class	Subclass
	1	20010009031	2001-07-19	Nitta et al.	A1		
	2	20030025205	2003-02-06	Shively	A1		

Signature

Examiner Name	Date